

**AMENDMENTS TO THE SPECIFICATION:**

*Please amend the paragraph beginning at page 21, line 7, and continuing to page 21, line 16, as follows:*

The means (pressure applying means) to apply pressure on the semiconductor element 3 is not particularly limited, and a conventionally known pressure applying tool can be suitably used. A pulse heating tool is particularly preferable. The conditions for applying pressure are not particularly limited, so long as the applied pressure does not break the semiconductor element 3 but is strong enough to push out the insulating resin 7 and to sufficiently make electrical connections between the projecting electrodes 6 and the contacts 4. As understood from Fig. 1, the pushing out of the insulating resin 7 to accomplish the electrical connection means that insulating resin 7 effectively seals the projecting electrode 6 in electrical contact with the interconnection pattern.